IN THE SPECIFICATION

Please amend the Title of the Invention as follows:

-- A RESIN-ENCAPSULATED SEMICONDUCTOR DEVICE COMPRISING A DIE PAD AND A PLURALITY OF LEADS PROVIDED BY REMOVING PREDETERMINED PORTION OF A LEAD FRAME --

Please replace the following paragraph beginning at page 8 line 3 and ending at page 8, line 5 with the following rewritten paragraph:

-- FIG. 4A and FIG. 4B are cross-sectional views illustrating the process of manufacturing the resin-encapsulated semiconductor device of the first embodiment, up to the step of forming leads. FIG. 4C is a cross-sectional area illustrating the semiconductor device of the first embodiment with the semiconductor chip's principal surface facing down.

Please replace the following paragraph beginning at page 11 line 1 and ending at page 11, line 8 with the following rewritten paragraph:

-- First, in the step shown in FIG. 3A, a lead-frame-forming metal plate made of a copper-based material, for example, and having a thickness of 200 to 300 μm is prepared, and the metal plate is etched, for example, so as to form a lead frame including a semi-finished die pad 2a, semi-finished leads 3a, unmachined suspension leads (not shown) for supporting the die pad 2 at their tips, and an outer frame (not shown) to which the ends of the semi-finished leads 3a and the unmachined suspension leads are connected. Note that in the illustrated example, the semi-finished die pad 2a is in a square or rectangular shape, and the semi-finished leads 3a are provided along the four sides of the square or rectangular shape so as to oppose one another. --

Please replace the following paragraph beginning at page 15 line 9 and ending at page 15, line 16 with the following rewritten paragraph:

-- Note that in the resin-encapsulated semiconductor device of the present embodiment, the thin metal wire 4 is used for the connection between the lead 3 and the electrode pad of the semiconductor chip 1. Alternatively, a bump made of a conductor may be used. In this way, it is possible to produce a flip chip that is thinner than those in the prior art, and it is also possible to further increase the size of the semiconductor chip to be mounted. In such a case as shown in Fig. 4C, the semiconductor chip 1 is mounted on the die pad 2 with its principal surface facing down, and the semiconductor chip 1 is connected with bumps 18 provided on the leads 3. --